EK-TM4C123GXL-BOOSTXL-BREAKOUT Firmware Development Package

USER'S GUIDE

SW-EK-TM4C123GXL-BOOSTXL-BREAKOUT-UG-2.1.1.71

Copyright

Texas Instruments
108 Wild Basin, Suite 350
Austin, TX 78746
www.ti.com/tiva-c

Revision Information

This is version 2.1.1.71 of this document, last updated on May 07, 2015.

Table of Contents

1 Introduction

This document describes the example applications that are provided for the EK-TM4C123GXL when paired with the BOOSTXL-IOBKOUT BoosterPack. The GPIO Breakout BoosterPack is a low-cost IO breakout board for the Texas Instruments® Tiva™ C Series LaunchPad BoosterPack XL pinout. Every available signal is connected to a 0.1-inch header position in addition to the majority being connected to 3.5-mm screw terminals for easy access when prototyping. Every digital signal is ESD protected and every analog signal is routed through a unity-gain amplifier to simplify development with a Tiva C Series Launchpad.

Features

- 3.5-mm screw terminal for all unused I/O
- 8 analog
- 22 digital
- 2 3.3-V terminals
- 4 ground terminals
- Analog channels equipped with unity-gain amplifiers
- ESD protection on every I/O signal and power rail
- 3-position user DIP switch
- Plated through-holes on a 0.1-inch grid for each I/O signal
- Six 0.125"-diameter mounting holes
- Dual HID gamepad demo

See the GPIO Breakout BoosterPack User's Guide for more detailed information on this booster pack at `http://www.ti.com/tool/boostxl-iobkout`

2 Example Applications

The example applications show how to use features of the Cortex-M4F microprocessor, the peripherals on the Tiva C Series microcontroller, and the drivers provided by the peripheral driver library. These applications are intended for demonstration and as a starting point for new applications.

There is an IAR workspace file (`ek-tm4c123gxl-boostxl-breakout.eww`) that contains the peripheral driver library project, USB library project, and all of the board example projects, in a single, easy to use workspace for use with Embedded Workbench version 6.

There is a Keil multi-project workspace file (`ek-tm4c123gxl-boostxl-breakout.mpw`) that contains the peripheral driver library project, USB library project, and all of the board example projects, in a single, easy to use workspace for use with uVision.

All of these examples reside in the `examples/boards/ek-tm4c123gxl-boostxl-breakout` subdirectory of the firmware development package source distribution.

2.1 USB HID Composite Gamepad (usb_dev_cgamepad)

This example application enables the evaluation board to act as a dual USB game pad device supported using the Human Interface Device class. The mapping of the analog pin to gamepad axis and GPIO to button inputs are listed below.

Analog Pin Mapping:

- Gamepad 1 X Axis - PE2/AIN1
- Gamepad 1 Y Axis - PE1/AIN2
- Gamepad 1 Z Axis - PD3/AIN4
- Gamepad 1 Rx Axis - PD2/AIN5
- Gamepad 2 X Axis - PD1/AIN6
- Gamepad 2 Y Axis - PD0/AIN7
- Gamepad 2 Z Axis - PE5/AIN8
- Gamepad 2 Ry Axis - PB5/AIN11

Button Pin Mapping.

- Gamepad 1 Button 1 - PF4
- Gamepad 1 Button 2 - PE0
- Gamepad 1 Button 3 - PE3
- Gamepad 1 Button 4 - PE4
- Gamepad 1 Button 5 - PB4
- Gamepad 1 Button 6 - PB3
- Gamepad 1 Button 7 - PB2
- Gamepad 1 Button 8 - PB0
- Gamepad 1 Button 9 - PB1
- Gamepad 1 Button 10 - PA6

- Gamepad 1 Button 11 - PA7

- Gamepad 2 Button 1 - PF0
- Gamepad 2 Button 2 - PC4
- Gamepad 2 Button 3 - PC5
- Gamepad 2 Button 4 - PC6
- Gamepad 2 Button 5 - PC7
- Gamepad 2 Button 6 - PD6
- Gamepad 2 Button 7 - PD7
- Gamepad 2 Button 8 - PA5
- Gamepad 2 Button 9 - PA4
- Gamepad 2 Button 10 - PA3
- Gamepad 2 Button 11 - PA2

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer’s risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

"So long and thanks for all the fish." - Douglas Adams

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265